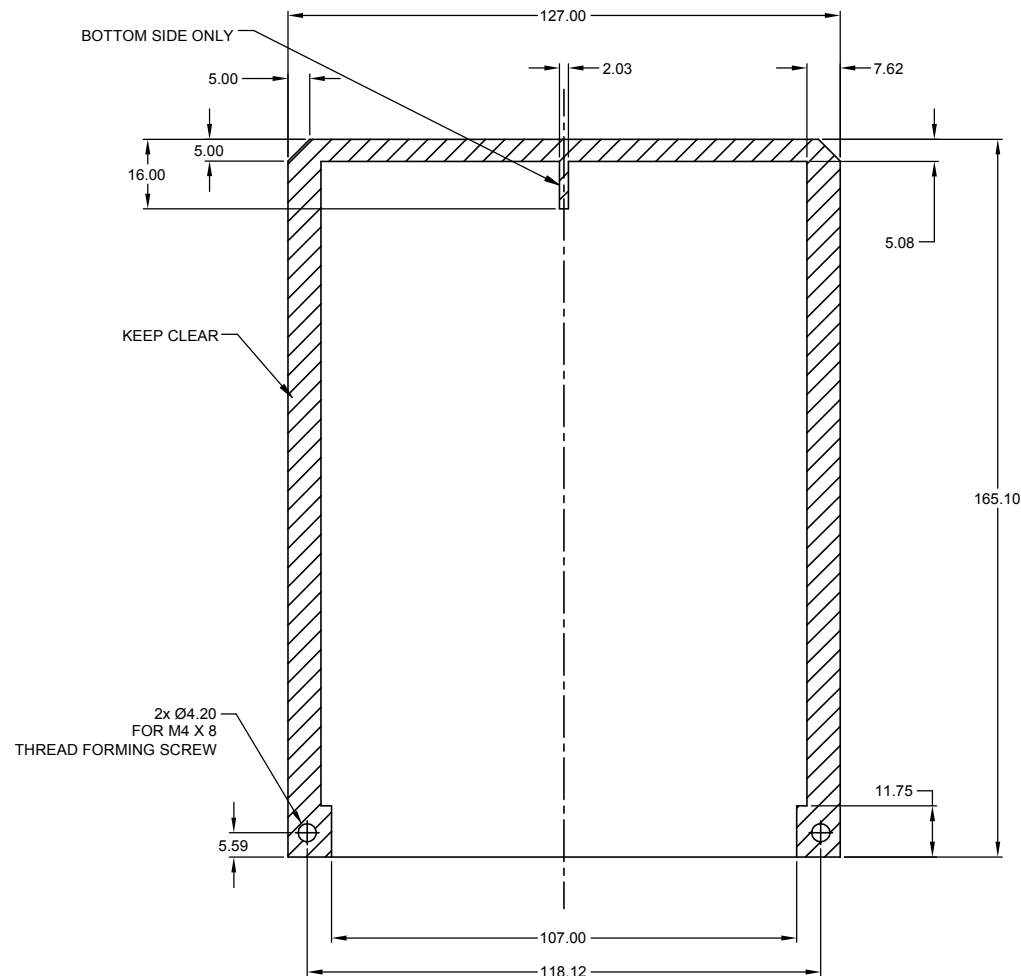
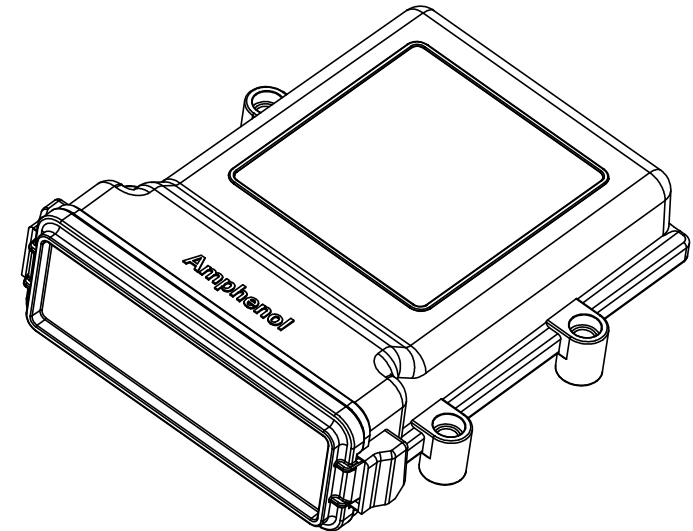


REVISIONS					
REV	ECO	DESCRIPTION	DATE	BY	APPR
A1	-	NEW RELEASE	28APR2020	ZENIN	TOMMY



CIRCUIT BOARD HOLE LOCATIONS AND KEEP CLEAR AREAS
 BOARD THICKNESS IN KEEP CLEAR ARE TO BE 2.36±0.1
 MAX. COMPONENT HEIGHT UPSIDE BOARD 25.20 mm.
 MAX. COMPONENT HEIGHT UNDER BOARD 4.00 mm.
 ALL DIMENSIONS REFERENCE
 TOP VIEW



3D VIEW
 AIPXE-5X650A-XXXX AND
 AIPXE-5X650B-XXXX ENCLOSURE AND
 MOUNTING HARDWARE SHOWN FOR REFERENCE

AIPXE-5X650BP-01		DESCRIPTION		ITEM
PART NUMBER				
QUANTITY	MATERIALS LIST			
UNLESS OTHERWISE SPECIFIED 1) All dimensions are in metric(mm). 2) Tolerances are as follows: 1 PL DEC ±0.30 2 PL DEC ±0.15 3 PL DEC ±0.08 3) Note reference = 		SIGNATURES DRAWN: ZENIN,DENG CHECKED: ORION,LI ENGINEER: APPROVAL: TOMMY,XIE		DATE 28/APR/20 29/APR/20 30/APR/20
MATERIAL SPECIFICATIONS:		CUSTOMER:		<div>Sine Systems - www.amphenol-sine.com 44724 Morley Drive Clinton Township, MI 48036</div> <div>ARMOR IPX, BLANK PLATE FOR AT</div>
PROCESS SPECIFICATIONS:		THIS DRAWING IS SUPPLIED FOR INFORMATION ONLY. DESIGN FEATURES, SPECIFICATIONS AND PERFORMANCE DATA SHOWN HEREON ARE THE PROPERTY OF THE AMPHENOL CORPORATION. NO RIGHTS OF REPRODUCTION ARE IMPLIED. ALL DIMENSIONS ARE SUBJECT TO NORMAL MANUFACTURING VARIATIONS.		
NEXT ASSY:		SCALE: NONE		
		SIZE TYPE B C-		DWG NO: AIPXE-5X650BP-01
				REVISION A1
				SHEET 2 OF 2